

RSS090P03-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d Q _g (Typ.)			
- 30	0.011 at V _{GS} = - 10 V	- 11.6	22 nC		
- 30	0.012 at V _{GS} = - 4.5 V	- 10	22 110		

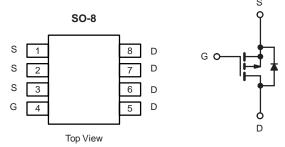
FEATURES

- Halogen-free According to IEC 61249-2-21 **Available**
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested





- · Load Switches
 - Notebook PCs
 - Desktop PCs



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T	A = 25 °C, unless other	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage		V_{GS}	± 20	V
	T _C = 25 °C		- 11.6	
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C	1 1	- 10.5	
Continuous Diam Current (1) = 130 C)	T _A = 25 °C	l ID	- 8.7 ^{a, b}	
	T _A = 70 °C		- 7.7 ^{a, b}	A
Pulsed Drain Current	I _{DM}	- 40	A	
Continuous Course Drain Diada Current	T _C = 25 °C	1-	- 4.6	
Continuous Source-Drain Diode Current	T _A = 25 °C	l _S	2.0 ^{a, b}	
Avalanche Current	1 04 11	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		5.6	
Mayimum Dawar Dissination	T _C = 70 °C	ь	3.6	w
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	VV
	T _A = 70 °C		1.6 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	39	50	°C/W	
Maximum Junction-to-Foot	Steady State	R_{thJF}	18	22	- C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W. d. Based on $T_{\rm C}$ = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-					<u>I</u>	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250A		- 31		1406	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		5.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA	
7 0 1 1/1 5 1 0 1		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5		
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ - 10 V, V _{GS} = - 10 V	- 30			Α	
		V _{GS} = - 10 V, I _D = - 10 A		0.011		+ -	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 7 A		0.012		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		23		S	
Dynamic ^b				L		I.	
Input Capacitance	C _{iss}			1960			
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		380		pF	
Reverse Transfer Capacitance	C _{rss}			325			
T. 10		V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 10 A		43	65		
Total Gate Charge	$Q_g = \frac{V_{DS} - 10 \text{ v, } V_{GS} - 10 \text{ v, } V_{DS} - 10 \text{ v}}{V_{DS} - 10 \text{ v, } V_{DS} - 10 \text{ v}}$		22	33			
Gate-Source Charge	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 10 A		6		nC	
Gate-Drain Charge	Q_{gd}			11		1	
Gate Resistance	R_g	f = 1 MHz	0.3	1.3	2.5	Ω	
Turn-On Delay Time	t _{d(on)}			11	22		
Rise Time	ì,	$V_{DD} = -15 \text{ V}, R_{L} = 3 \Omega$		13	25		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		32	50		
Fall Time	t _f			9	18		
Turn-On Delay Time	t _{d(on)}			44	70	ns	
Rise Time	ì,	$V_{DD} = -15 \text{ V}, R_{L} = 3 \Omega$		100	160		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		28	50		
Fall Time	ì,			15	30		
Drain-Source Body Diode Characterist	ics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.6	_	
Pulse Diode Forward Current	I _{SM}				- 50	Α	
Body Diode Voltage	V _{SD}	I _S = -2 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	- 55		28	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 0 A 41/44 400 A/22 T 05 00		20	40	nC	
Reverse Recovery Fall Time	t _a	$I_F = -2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		13			
Reverse Recovery Rise Time	t _b	1		15		ns	

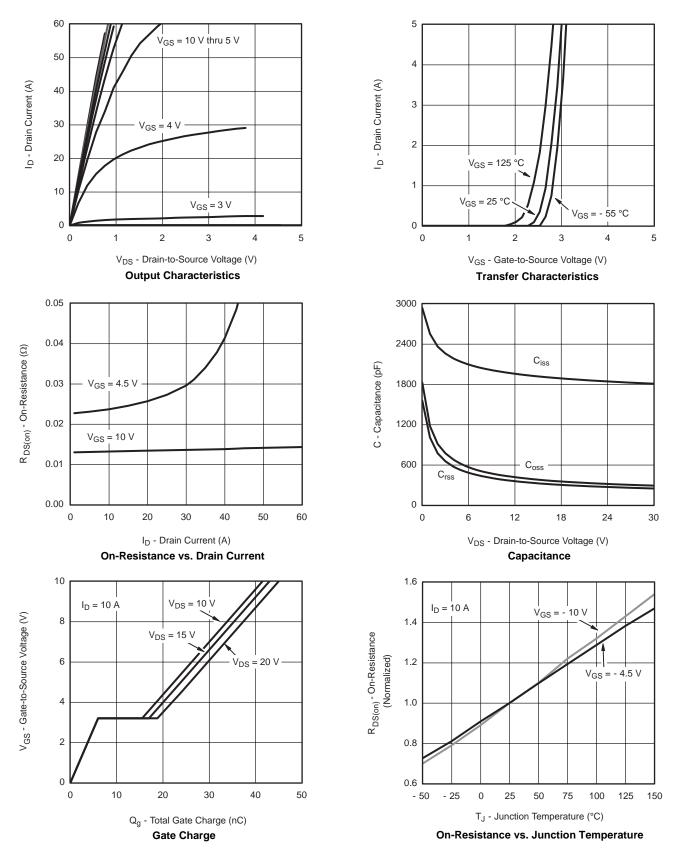
Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

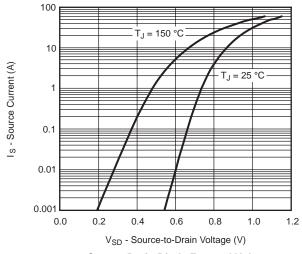
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

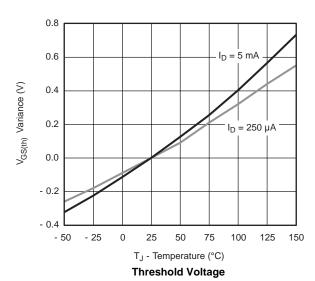


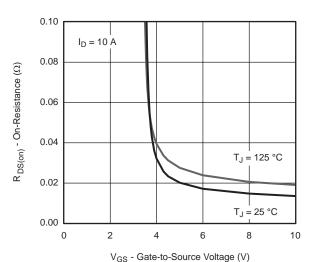




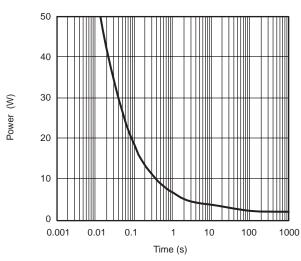


Source-Drain Diode Forward Voltage

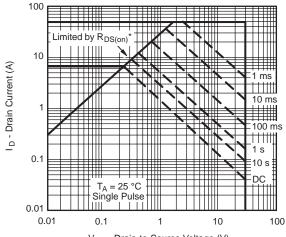




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

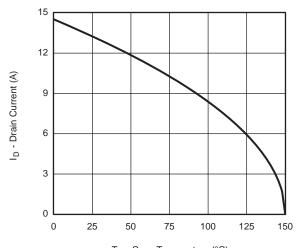


V_{DS} - Drain-to-Source Voltage (V)

* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

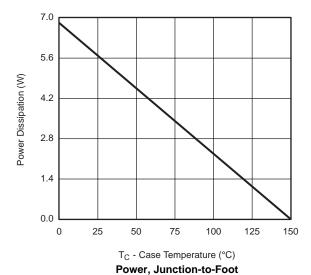
Safe Operating Area

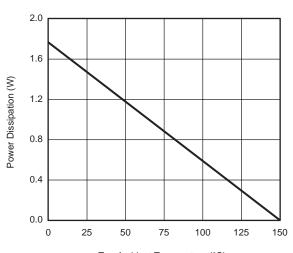




 $T_{\mbox{\scriptsize C}}$ - Case Temperature (°C)

Current Derating*

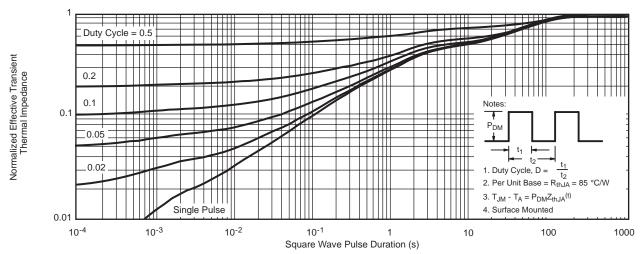




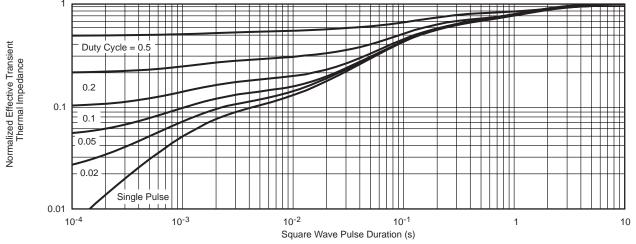
T_A - Ambient Temperature (°C) **Power Derating, Junction-to-Ambient**

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

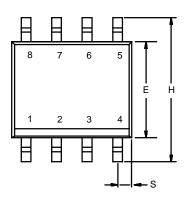


Normalized Thermal Transient Impedance, Junction-to-Foot

服务热线:400-655-8788 6



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







	MILLIMETERS		MILLIMETERS INCHES		
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
FCN: C-06527-Rev I 11-Sen-06					

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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